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(54) ADHESIVE SILICONE COMPOSITION FOR HEAT RADIATION MEMBER

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a heat radiation member that has excellent heat radiation performance by compounding a large amount of thermally conductive filler and reducing the interfacial contact heat resistance by making the surface adherent.

SOLUTION: The adhesive silicone composition for heat radiation members comprises (A) 100 pts.wt. of a curable silicone adhesive including an organopolysiloxane of (a) $R_1SiO_{1/2}$ unit (wherein R_1 is independently a 1-6C monovalent hydrocarbon group other than alkenyl) and SiO_2 unit where the molar ratio of $R_1SiO_{1/2}$ unit to SiO_2 unit is 0.6 to 1.7; (B) 500 to 3,000 pts.wt. of thermally conductive filler and (C) 0.1 to 50 pts.wt. of an organosilane represented by general formula (1) $R_2aR_3bSi(OR_4)_{4-a-b}$ (1) (wherein R_2 is a 6-15C monovalent alkyl group; R_3 is an unsubstituted or substituted 1-8C monovalent hydrocarbon group; R_4 is independently a 1-6C monovalent hydrocarbon group; a is an integer of 1 to 3; b is 0 or an integer of 1 or 2; the sum of $a+b$ is an integer of 1-3).

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